2SC4892

Silicon NPN triple diffusion planar type

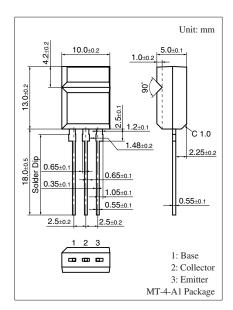
For power switching

Features

- High-speed switching
- High collector-base voltage (Emitter open) V_{CBO}
- \bullet Satisfactory linearity of forward current transfer ratio h_{FE}
- Allowing supply with the radial taping

Parameter	Symbol	Rating	Unit	
Parameter		Symbol	паші	Unit
Collector-base voltage (En	V _{CBO}	900	V	
Collector-emitter voltage (E-B short)		V _{CES}	900	V
Collector-emitter voltage (Base open)		V _{CEO}	800	V
Emitter-base voltage (Collector open)		V _{EBO}	7	V
Base current		IB	0.3	А
Collector current	I _C	1	А	
Peak collector current		I _{CP}	2	А
Collector power dissipation		P _C	15	W
	$T_a = 25^{\circ}C$		2	
Junction temperature		Tj	150	°C
Storage temperature		T _{stg}	-55 to +150	°C



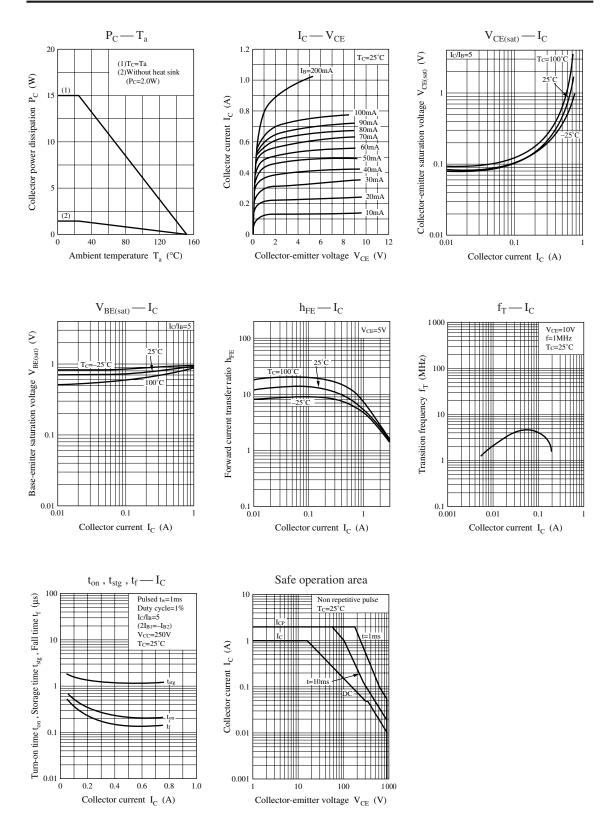


Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

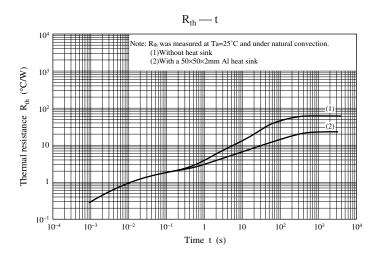
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$	800			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 900 \text{ V}, I_E = 0$			50	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 5 \text{ V}, I_C = 0.05 \text{ A}$	6			
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_C = 0.5 \text{ A}$	3			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 0.2 \text{ A}, I_{\rm B} = 0.04 \text{ A}$			1.5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{\rm C} = 0.2 \text{ A}, I_{\rm B} = 0.04 \text{ A}$			1.0	V
Transition frequency	f _T	$V_{CE} = 10 \text{ V}, I_C = 0.05 \text{ A}, f = 1 \text{ MHz}$		4		MHz
Turn-on time	t _{on}	$I_{\rm C} = 0.2 {\rm A}$			1.0	μs
Storage time	t _{stg}	$I_{B1} = 0.04 \text{ A}, I_{B2} = -0.08 \text{ A}$			3.0	μs
Fall time	t _f	$V_{CC} = 250 \text{ V}$			1.0	μs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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